



IBM Docket No. FIS920030024US1

Date of Deposit: September 18, 2003

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9/18/03

In the United States Patent and Trademark Office

Date: September 18, 2003

In re Application William Wille et al.
of:

Filed: June 24, 2003

For: METHOD FOR FORMING DAMASCENE STRUCTURE
UTILIZING PLANARIZING MATERIAL COUPLED WITH
DIFFUSION BARRIER MATERIAL

Serial Number: 10/604,056

Art Unit:

Examiner:

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. § 1.56, and further pursuant to the provisions of 37 C.F.R. §§ 1.97 and 1.98, Applicants hereby respectfully submit copies of the prior publications as listed on Form PTO-1449, attached hereto. Applicants also hereby submit a copy of the following pending U.S. patent application:

Ser. No.: 09/256, 034

Filing Date: February 23, 1999

Attorney Docket No.: YO998-056

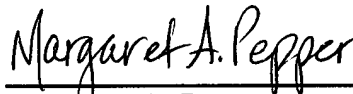
Inventors: M. Angelopoulos et al.

Title: Multilayered Resist System Using Tuned Polymer Films as Underlayers
and Methods of Fabrication Thereof

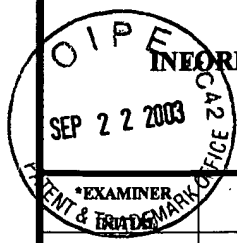
In citing these documents, no representation is made nor intended as to the pertinency or non-pertinency of the art, that better art than listed is not available, or that other art is not applicable.

Pursuant to 37 C.F.R. §§ 1.97(b), no fee is believed to be due for this submission. If any fees are required, however, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 09-0458.

Respectfully Submitted,



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INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

FIS920030024US1

Application Number

10/604,056

Applicant(s)

William Wille, et al.

Filing Date

6/24/03

Group Art Unit

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

"A High Performance 0.13 um Copper BEOL Technology with Low-K Dielectric" R.D. Goldblatt, et al. Proceedings of the IEEE 2000 International Interconnect Technology Conference, 5-7 June, 2000, pp. 261-263.

"A Manufacturable Copper/Low-k SiOC/SiCN Process Technology for 90nm-node High Performance eDRAM", K. Higashi, et al., Proceedings of the IEEE 2002 International Interconnect Technology Conference, 3-5 June 2002, pp. 15-17.

"A High Resolution 248 nm Bilayer Resist" Qinghuang Lin, et al., Proc. SPIE - Int. Soc. Opt. Eng. (USA), vol. 3678, pt. 1-2, pp. 241-50.

"Surface treatment validation of inorganic BARC on 0.25 um Non Volatile Memory technology", Y. Trouilleret al. Microelectronic Engineering 46 (1999), pp. 47-50.

"Effects of Crosslinking Agent on Lithographic Performance of Negative-Tone Resists Based on Poly (p-hydroxystyrene)", Qinghuang Lin, et al. Proc. SPIE - Int. Soc. Opt. Eng. (USA), vol 3049, pp. 974-87.

Patent Application, Serial Number 09/256,034, dated 2/23/99, Inventors M. Angelopoulos, et al. Entitled Multilayered Resist System Using Tuned Polymer Films as Underlayers and Methods of Fabrication Thereof.

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.